

features

- 10-Bit, 25-MSPS, Analog-to-Digital Converter (ADC)
- Single Power Supply Operation, 2.7 V to 3.3 V
- Low Power: 95 mW at 2.7 V, Power-Down Mode: 1 mW
- Full-Channel Differential-Nonlinearity Error: $<\pm 0.5$ LSB Typical
- Full-Channel Integral-Nonlinearity Error: $<\pm 1.5$ LSB Typical
- Dual Input Modes: CCD and Video
- Programmable-Gain Amplifier (PGA) With 0-dB to 36-dB Gain Range (0.047 dB/Step) for CCD Mode, 0-dB to 12-dB Gain Range (0.047 dB/Step) for Video Mode
- Serial Interface for Register Configuration
- Programmable Black-Level and Offset Calibration
- Analog Gain Implementation With Specified No Missing Code, Even At High Gains
- Additional Digital-to-Analog Converters (DACs) for External Analog Setting
- Internal Reference Voltages
- Programmable Internal-Timing Signal Delays
- 48-Terminal TQFP Package

applications

- Digital Still Camera
- Digital Camcorder
- Digital Video Camera

description

The VSP1021 device is a highly-integrated monolithic analog-signal processor/digitizer designed to interface the area charge-coupled-device (CCD) sensors in digital-camera and camcorder applications. The VSP1021 device performs all the analog processing functions necessary to maximize the dynamic range, corrects various errors associated with the CCD sensor, and then digitizes the results with an on-chip, high-speed ADC. The key components of the VSP1021 device include:

- Input clamp circuitry and a correlated double sampler (CDS)
- Programmable-gain amplifier (PGA) with 0-dB to 36-dB gain range for CCD mode and 0-dB to 12-dB range for video mode
- Two internal DACs for automatic or programmable optical-black-level and offset calibration
- 10-bit, 25-MSPS pipeline ADC for CCD mode and a 28-MSPS ADC for video mode
- Parallel data port for easy microprocessor interface and a serial port for configuring internal control registers
- Two additional DACs for external system control
- Internal reference voltages

The VSP1021 device is designed using advanced CMOS process and operates from a single 3-V power supply with a normal power consumption of just 95 mW, and 1 mW in power-down mode.

High throughput rate, single 3-V operation, very-low-power consumption, and fully-integrated analog-processing circuitry make the VSP1021 device an ideal CCD and video-signal-processing solution for electronic video-camcorder applications.

This device is available in a 48-terminal TQFP package and is specified over an operating temperature range of -20°C to 75°C .

AVAILABLE OPTIONS

T _A	PACKAGE TQFP (PFB)
-20°C to 75°C	VSP1021PFB



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
INSTRUMENTS**

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
VSP1021PFB	NRND	TQFP	PFB	48	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		VSP1021	
VSP1021PFBG4	NRND	TQFP	PFB	48	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR		VSP1021	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

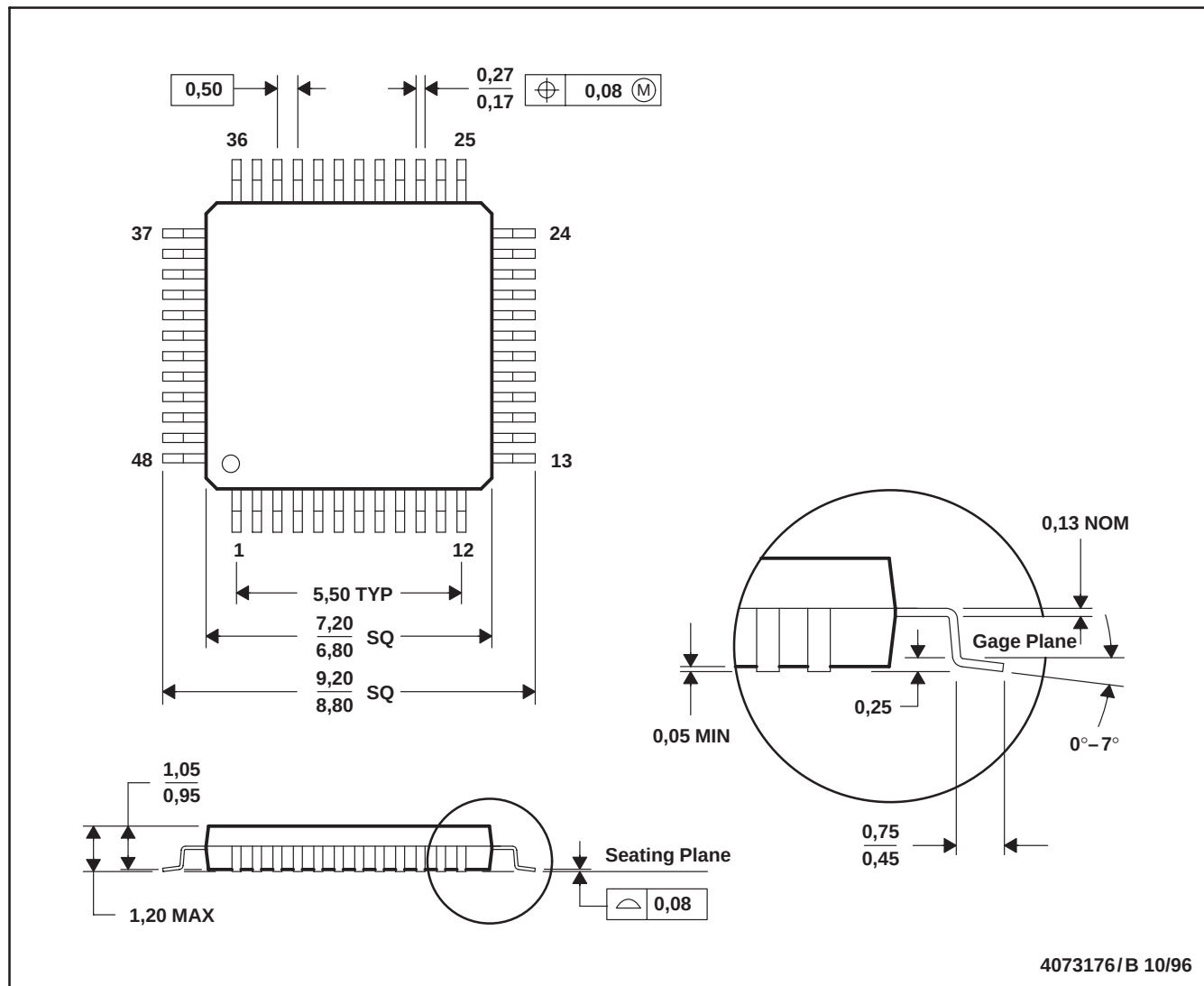
(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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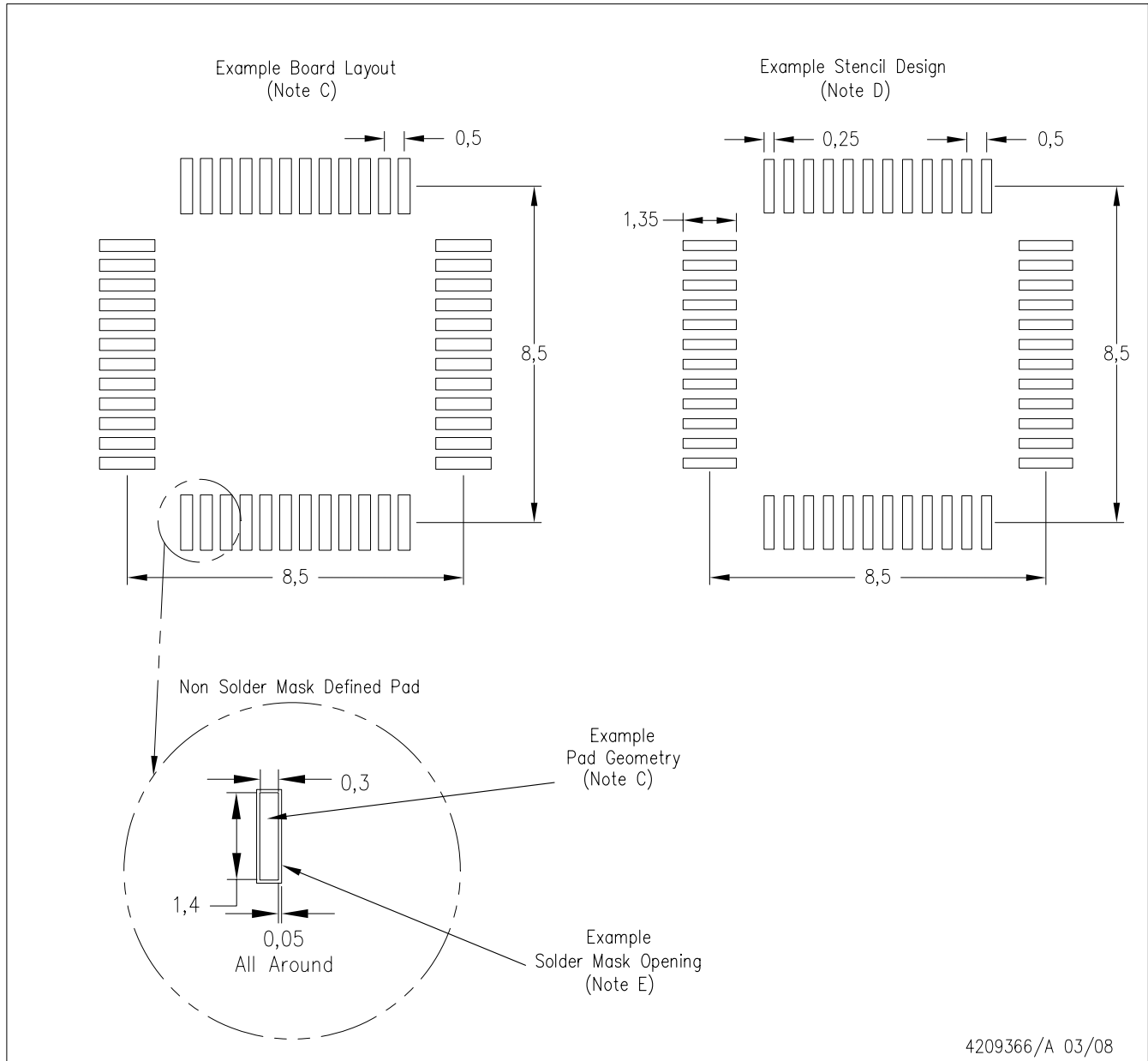
PFB (S-PQFP-G48)

PLASTIC QUAD FLATPACK



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-026

PFB (S-PQFP-G48)



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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